

LTM2884-BGA-44LEAD-PBF- 15mm X 15mm X 5.02mm (TABLE OF MATERIAL DECLARATION)							
The LTM2884 is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2639	Barium Compounds	7727-43-7	0.00625	2.37
				Bismaleimide/Triazine Resin/filter Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure.	0.07816	29.62
				Copper Metal	7440-50-8	0.10019	37.97
				Copper Compounds	147-14-8	0.00006	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.00
				Gold metal or alloy	7440-57-5	0.00047	0.18
				Nickel	7440-02-0	0.00314	1.19
				Zinc	7440-66-6	0.00010	0.04
				Bisphenol A epoxyresin	25068-38-6	0.00002	0.01
				Continuous Filament Fiber Glass	65997-17-3	0.06143	23.28
				Acrylic Resin	non-disclosure	0.01193	4.52
				Epoxy Resin	non-disclosure	0.00022	0.09
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00008	0.03
				Talc;not containing fibers like asbestos	14807-96-9	0.00071	0.27
				Aromatic Carbonyl compounds	non-disclosure	0.00069	0.26
				Cyanoguanidine	461-58-5	0.00002	0.01
				Amine compounds	non-disclosure	0.00009	0.03
				Leveling agent and others	non-disclosure	0.00026	0.10
				Imidazole system curing agent	non-disclosure	0.00002	0.01
2	Solder Paste	Alloy	0.0582	Sn	7440-31-5	0.05531	95.00
				Sb	7440-36-0	0.00291	5.00
3	Epoxy		0.0055	Di-ester resin	non-disclosure	0.00055	10.00
				Functionalized ester	non-disclosure	0.00055	10.00
				Silver	7440-22-4	0.00438	80.00
4	Passive/Active Components		0.5094	Ni Oxide	1313-99-1	0.03111	6.11
				Cu Oxide	1317-38-0	0.01047	2.05
				Zn Oxide	1314-13-2	0.04738	9.30
				Fe Oxide	1309-37-1	0.17264	33.89
				Iron Powder (Fe)	7439-89-6	0.00506	0.99
				Copper (Cu)	7440-50-8	0.12067	23.69
				Nickel (Ni)	7440-02-0	0.01382	2.71
				Tin (Sn)	7440-31-5	0.00882	1.73
				Ceramic (Ba) Compounds	12047-27-7	0.09944	19.52
5	Active Ics	Silicon	0.0064	Silicon	7440-21-3	0.00644	100.00
6	Wire	Gold	0.0102	Au	7440-57-5	0.01022	99.99
	Solder Ball	SAC305	0.2222	Sn	7440-31-5	0.21444	96.50
				Ag	7440-22-4	0.00667	3.00
				Cu	7440-50-8	0.00111	0.50
7	Encapsulation	Epoxy Resin	1.4275	Fused Silica	60676-86-0	1.10204	77.20
				Epoxy Resin	non-disclosure	0.12705	8.90
				Phenol Resin	non-disclosure	0.12705	8.90
				Crytalline Silica	14808-60-7	0.04283	3.00
				Carbon Black	1333-86-4	0.00714	0.50
				Metal Hydroxide	non-disclosure	0.02141	1.50
Total Package Weight			2.5033				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts